

PTO/SB/17 (05-03)

Approved for use through 04/30/2003. OMB 0851-0032
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

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**FEE TRANSMITTAL
for FY 2003**

Effective 01/01/2003. Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27**TOTAL AMOUNT OF PAYMENT**

(\$ 84.00)

Complete if Known

Application Number	10/045,354
Filing Date	November 7, 2001
First Named Inventor	Angela Hui et al.
Examiner Name	Khiem D. Nguyen
Art Unit	2823
Attorney Docket No.	AMDP714US

METHOD OF PAYMENT (check all that apply)
☐ Check ☐ Credit card ☐ Money Order ☒ Other ☐ None
☒ Deposit Account:

Deposit Account Number	50-1733
Deposit Account Name	ESCHWEILER & ASSOCIATES, LLC

The Director is authorized to: (check all that apply)

☒ Charge fee(s) indicated below ☒ Credit any overpayments
☐ Charge any additional fee(s) during the pendency of this application
☐ Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.
FEE CALCULATION**1. BASIC FILING FEE**

Large Entity		Small Entity		Fee Description	Fee Paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
1001	750	2001	375	Utility filing fee	
1002	330	2002	165	Design filing fee	
1003	520	2003	260	Plant filing fee	
1004	750	2004	375	Reissue filing fee	
1005	180	2005	80	Provisional filing fee	

SUBTOTAL (1) (\$ --)**2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE**

Total Claims		Extra Claims		Fee below		Fee Paid	
Independent	25	-26** =	-	X	18.00	=	-
Multiple Dependent	5	-4** =	1	X	84.00	=	84.00

Large Entity		Small Entity		Fee Description
Fee Code	Fee (\$)	Fee Code	Fee (\$)	
1202	18	2202	9	Claims in excess of 20
1201	84	2201	42	Independent claims in excess of 3
1203	280	2203	140	Multiple dependent claim, if not paid
1204	84	2204	42	** Reissue independent claims over original patent
1205	18	2205	9	** Reissue claims in excess of 20 and over original patent

SUBTOTAL (2) (\$ 84.00)

**or number previously paid, if greater; For Reissues, see above

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Entity		Small Entity		Fee Description	Fee Paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
1051	130	2051	65	Surcharge - late filing fee or oath	
1052	50	2052	25	Surcharge - late provisional filing fee or cover sheet	
1053	130	1053	130	Non-English specification	
1812	2,520	1812	2,520	For filing a request for ex parte reexamination	
1804	920*	1804	920*	Requesting publication of SIR prior to Examiner action	
1805	1,840*	1805	1,840*	Requesting publication of SIR after Examiner action	
1251	110	2251	55	Extension for reply within first month	
1252	410	2252	205	Extension for reply within second month	
1253	930	2253	465	Extension for reply within third month	
1254	1,450	2254	725	Extension for reply within fourth month	
1255	1,970	2255	985	Extension for reply within fifth month	
1401	320	2401	160	Notice of Appeal	
1402	320	2402	160	Filing a brief in support of an appeal	
1403	280	2403	140	Request for oral hearing	
1451	1,510	1451	1,510	Petition to institute a public use proceeding	
1452	110	2452	55	Petition to revive - unavoidable	
1453	1,300	2453	650	Petition to revive - unintentional	
1501	1,300	2501	650	Utility issue fee (or reissue)	
1502	470	2502	235	Design issue fee	
1503	630	2503	315	Plant issue fee	
1460	130	1460	130	Petitions to the Commissioner	
1807	50	1807	50	Processing fee under 37 CFR 1.17(q)	
1806	180	1806	180	Submission of Information Disclosure Stmt	
8021	40	8021	40	Recording each patent assignment per property (times number of properties)	
1809	750	2809	375	Filing a submission after final rejection (37 CFR 1.129(a))	
1810	750	2810	375	For each additional invention to be examined (37 CFR 1.129(b))	
1801	750	2801	375	Request for Continued Examination (RCE)	
1802	900	1802	900	Request for expedited examination of a design application	

Other fee (specify)

*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$ --)**SUBMITTED BY**

Name (Print/Type) Thomas J. Eschweiler

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(Complete if applicable)

Telephone (216) 502-0600

Signature

Date

7/6/03

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paper No. 9

Docket No. AMDP714US

AF01159

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re **PATENT** application of:

Applicant: Angela Hui, et al.
Application No.: 10/045,354
For: AN INNOVATIVE METHOD OF HARD MASK REMOVAL
Filing Date: November 7, 2001
Examiner: Khiem D Nguyen
Art Unit: 2823

#9/C
7/11/03
VS

SUPPLEMENTAL REPLY TO OFFICE ACTION DATED APRIL 2, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Favorable reconsideration of the above-identified application is respectfully requested in view of the following amendments and remarks.

AMENDMENTS

IN THE CLAIMS:

Please amend claims 1, 19, 21 and 24, cancel claims 25-26, and add new claim 27 as follows below:

1. (Currently amended) A method of stripping a hard mask from a substrate comprising an insulating material exposed within gaps patterned through the hard mask, comprising:
- coating the substrate with a sacrificial material that fills the gaps; and
 - plasma etching to strip the sacrificial material and the hard mask substantially completely in a single plasma etch process.

Please enter the amendments
Paper No. 9
K.D.N.
07/11/03

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